



MJ N-Channel Enhancement Mode Power MOSFET

Description

The MJ40H30D uses advanced trench technology and design to provide excellent $R_{\text{DS}(\text{ON})}$ with low gate charge. It can be used in a wide variety of applications.

Application

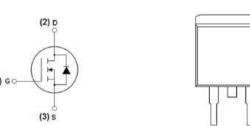
◆ Power switching application

Uninterruptible power supply

Hard switched and High frequency circuits

General Features

- $V_{DS} = 40V, I_{D} = 300A$ R_{DS(ON)} < 1.8mΩ @ V_{GS}=10V
- ◆ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation
- ◆ Special process technology for high ESD capability





Schematic diagram

Marking and pin assignment

TO-263-2L top view

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ40H30D	MJ40H30D	TO-263-2L	ii ii	-	2

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	40	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lb	300	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	212	А
Pulsed Drain Current	Ірм	840	А
Maximum Power Dissipation	Po	350	W
Derating factor		2.33	W/°C
Single pulse avalanche energy (Note 5)	Eas	2500	mJ
Operating Junction and Storage Temperature Range	TJ,TSTG	-55 To 175	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	0.43 °C/W
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Electrical Characteristics (TA =25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			1			
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =250µA	40	-	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =40V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	'					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	1.3	1.8	2.5	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V, I _D =150A	-	1.4	1.8	mΩ
Forward Transconductance	grs	V _{DS} =5V,I _D =150A	-	100	-	S
Dynamic Characteristics (Note 4)	ı	1	1			1
Input Capacitance	Clss		-	11635	-	PF
Output Capacitance	Coss	V _{DS} =25V,V _{GS} =0V F=1.0MHz	-	1360	-	PF
Reverse Transfer Capacitance	Crss	-	-	1229	-	PF
Switching Characteristics (Note 4)	'					
Turn-on Delay Time	t _{d(on)}		_	42	-	nS
Turn-on Rise Time	tr	V _{DD} =20V,RL=15Ω	-	41	-	nS
Turn-Off Delay Time	t _{d(off)}	R _G =2.5Ω,V _G s=10V	-	150	-	nS
Turn-Off Fall Time	t _f	-	-	70	-	nS
Total Gate Charge	Qg		-	249	-	nC
Gate-Source Charge	Qgs	I _D =150A,V _{DD} =20V V _{GS} =10V	-	40	-	nC
Gate-Drain Charge	Qgd	_	_	80	-	nC
Drain-Source Diode Characteristics	I	1				I.
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =150A	_	0.85	1.2	V
Diode Forward Current (Note 2)	ls		-	-	300	А
leverse Recovery Time t _{rr}		TJ=25°C, IF=300A	-	55	-	nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs (Note 3)	_	180	-	nC

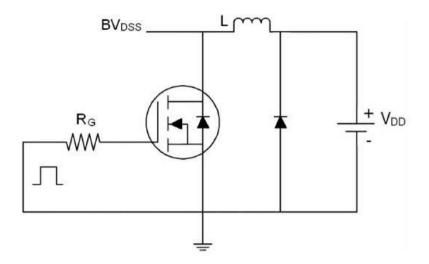
Notes:

- 1 Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- Guaranteed by design, not subject to production
- 5 EAS condition: Tj=25 $^{\circ}$ C,Vpp=20V,Vg=10V,L=0.5mH,Rg=25 Ω

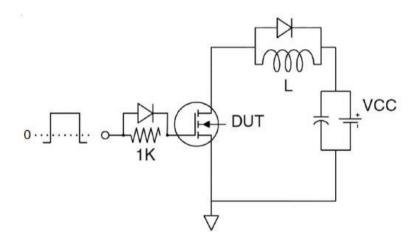




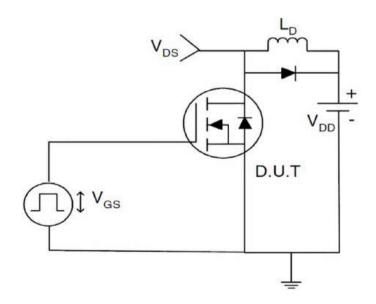
Test circuit



Eas test Circuit



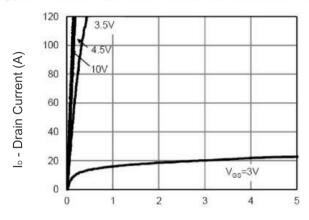
Gate charge test Circuit

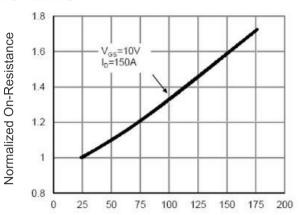


Switch Time Test Circuit



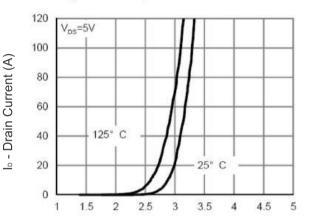
Typical Electrical and Thermal Characteristics (Curves)





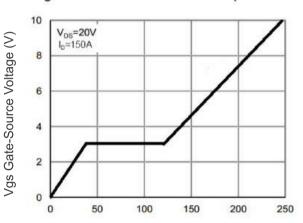
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



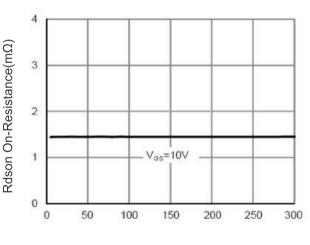
 T_{J} -Junction Temperature(${}^{\circ}\mathsf{C}$)

Figure 4 Rdson-Junction Temperature

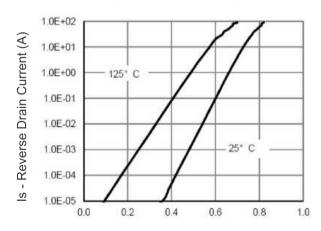


Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge



l₀ - Drain Current (A)

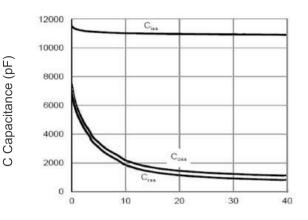
Figure 3 Rdson- Drain Current

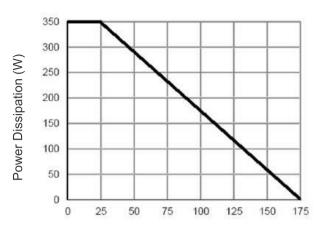
Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward



lo - Drain Current (A)



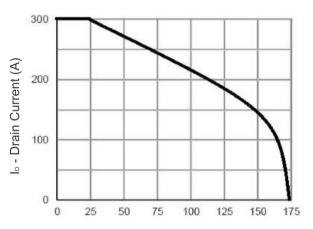




Vds Drain-Source Voltage (V) Figure 7 Capacitance vs Vds

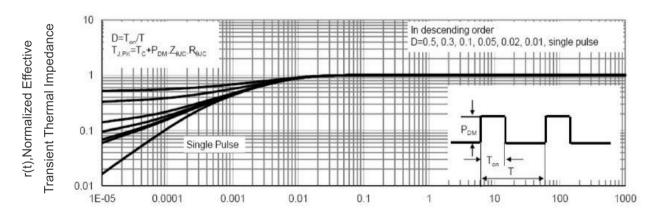
1000.0 10µs R_{DS(ON)} limited 100.0 100µs 10.0 10ms DC 1.0 T_{J(Max)}=175° C T_C=25° C 0.1 0.0 0.01 10 100 1000

T_J -Junction Temperature(°C) Figure 9 Power De-rating



Vds Drain-Source Voltage (V) Figure 8 Safe Operation Area

T_J -Junction Temperature(°C) Figure 10 Current De-rating



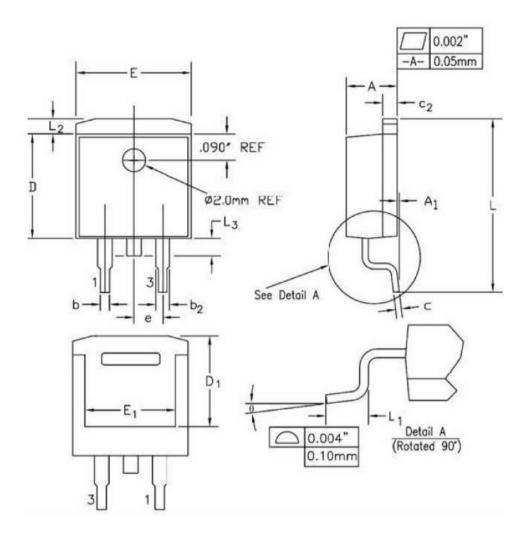
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





TO-263-2L Package Information



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	NOTES
Α	0.170	0.180	4.32	4.57	
A1		0.010		0.25	
b	0.028	0.037	0.71	0.94	
b2	0.045	0.055	1.15	1.40	
С	0.018	0.024	0.46	0.61	
c2	0.048	0.055	1.22	1.40	
D	0.350	0.370	8.89	9.40	
D1	0.315	0.324	8.01	8.23	
E	0.395	0.405	10.04	10.28	
E1	0.310	0.318	7.88	8.08	
е	0.100 BSC.		2.54 BSC.		
L	0.580	0.620	14.73	15.75	
L1	0.090	0.110	2.29	2.79	
L2	0.045	0.055	1.15	1.39	
L3	0.050	0.070	1.27	1.77	
θ	0°	8°	0°	8°	
			+		



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